查询MC10EP105FAR2供应商

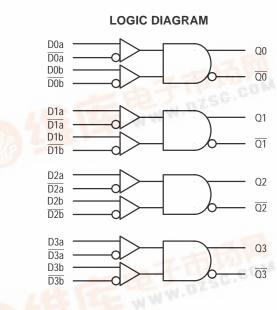
捷多邦,专业PCB打样工厂,24小时加急出货

MC10EP105

Product Preview Quad 2-Input Differential AND/NAND

The MC10EP105 is a 2–input differential AND/NAND gate. Each gate is functionally equivalent to a EP05 and LVEL05 devices. With AC performance much faster than the LVEL05 device, the EP105 is ideal for applications requiring the fastest AC performance available. All V_{CC} and V_{EE} pins must be externally connected to power supply to guarantee proper operation.

- 190ps Typical Propagation Delay
- High Bandwidth to 3 Ghz Typical
- ECL mode: 0V V_{CC} with $V_{EE} = -3.0V$ to -5.5V
- PECL mode: 3.0V to 5.5V V_{CC} with $V_{EE} = 0V$
- Internal Input Pulldown Resistors
- ESD Protection: >2KV HBM, >100V MM
- New Differential Input Common Mode Range
- Moisture Sensitivity Level 2
 For Additional Information, See Application Note AND8003/D
- Flammability Rating: UL–94 code V–0 @ 1/8", Oxygen Index 28 to 34
- Transistor Count = 444 devices



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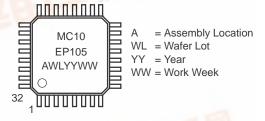
ON Semiconductor

Formerly a Division of Motorola http://onsemi.com

Concernation

32-LEAD TQFP FA SUFFIX CASE 873A

MARKING DIAGRAM*



*For additional information, see Application Note AND8002/D

PIN DESCRIPTION							
PIN	FUNCTION						
Dna, Dnb, Dna, Dnb	ECL Data Inputs						
Qn, Qn	ECL Data Outputs						
VBB	Reference Voltage Output						
VCC	Positive Supply						
VEE	Negative, 0 Supply						

TRUTH TABLE

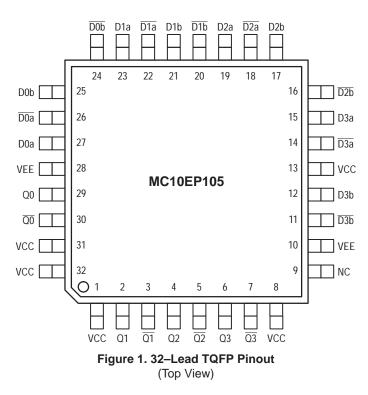
Dna	Dnb	Dna	Dnb	Qn	Qn
LLIII	LHLH	H H L	H L H L	L L H	H H L

ORDERING INFORMATION

Device	Package	Shipping
MC10EP105FA	TQFP	250 Units/Tray
MC10EP105FAR2	TQFP	2000 Tape & Reel

This document contains information on a product under development. ON Semiconductor

dzsc.com



Warning: All V_CC and V_EE pins must be externally connected to Power Supply to guarantee proper operation.

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V _{EE}	Power Supply ($V_{CC} = 0V$)	-6.0 to 0	VDC
VCC	Power Supply (V _{EE} = 0V)	6.0 to 0	VDC
VI	Input Voltage (V_{CC} = 0V, VI not more negative than V _{EE})	-6.0 to 0	VDC
VI	Input Voltage (V _{EE} = 0V, V _I not more positive than V _{CC})	6.0 to 0	VDC
l _{out}	Output Current Continu S	uous 50 urge 100	mA
Т _А	Operating Temperature Range	-40 to +85	°C
T _{stg}	Storage Temperature	-65 to +150	°C
θJA		II Air 80 Ifpm 55	°C/W
θJC	Thermal Resistance (Junction-to-Case)	12 to 17	°C/W
T _{sol}	Solder Temperature (<2 to 3 Seconds: 245°C desired)	265	°C

* Maximum Ratings are those values beyond which damage to the device may occur.

			–40°C			25°C		85°C			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
IEE	Power Supply Current (Note 1.)					59					mA
V _{OH} Output HIGH Voltage (Note 2.)		-1135	-1060	-885	-1070	-945	-820	-1010	-885	-760	mV
V _{OL}	Output LOW Voltage (Note 2.)	-1935	-1810	-1685	-1870	-1745	-1620	-1810	-1685	-1560	mV
VIH	Input HIGH Voltage Single Ended	-1210		-885	-1145		-820	-1085		-760	mV
VIL	Input LOW Voltage Single Ended	-1935		-1610	-1870		-1545	-1810		-1485	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Note 3.)	VEE	+2.0	0.0	VEE	+2.0	0.0	VEE	+2.0	0.0	V
Iн	Input HIGH Current			150			150			150	μΑ
ΙIL	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μA

DC CHARACTERISTICS, ECL/LVECL ($V_{CC} = 0V$; $V_{EE} = -5.5V$ to -3.0V) (Note 4.)

NOTE: 10EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

1. $V_{CC} = 0V$, $V_{EE} = V_{EEmin}$ to V_{EEmax} , all other pins floating. 2. All loading with 50 ohms to V_{CC} -2.0 volts. 3. V_{IHCMR} min varies 1:1 with V_{EE} , max varies 1:1 with V_{CC} . 4. Input and output parameters vary 1:1 with V_{CC} .

DC CHARACTERISTICS, LVPECL ($V_{CC} = 3.3V \pm 0.3V$, $V_{FF} = 0V$) (Note 8.)

			–40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
IEE	Power Supply Current (Note 5.)					59					mA
VOH	Output HIGH Voltage (Note 6.)	2165	2240	2415	2230	2355	2480	2290	2415	2540	mV
VOL	Output LOW Voltage (Note 6.)	1365	1490	1615	1430	1555	1680	1490	1615	1740	mV
VIH	Input HIGH Voltage Single Ended	2090		2415	2155		2480	2215		2540	mV
VIL	Input LOW Voltage Single Ended	1365		1690	1430		1755	1490		1815	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Note 7.)	2.0		3.3	2.0		3.3	2.0		3.3	V
IIН	Input HIGH Current			150			150			150	μΑ
Ι _Ι Γ	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μA

NOTE: 10EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

5. $V_{CC} = 3.3V$, $V_{EE} = 0V$, all other pins floating. 6. All loading with 50 ohms to V_{CC} -2.0 volts. 7. V_{IHCMR} min varies 1:1 with V_{EE} , max varies 1:1 with V_{CC} . 8. Input and output parameters vary 1:1 with V_{CC} .

			–40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
IEE	Power Supply Current (Note 9.)					59					mA
VOH	Output HIGH Voltage (Note 10.)	3865	3940	4115	3930	4055	4180	3990	4115	4240	mV
VOL	Output LOW Voltage (Note 10.)	3065	3190	3315	3130	3255	3380	3190	3315	3440	mV
VIH	Input HIGH Voltage Single Ended	3790		4115	3855		4180	3915		4240	mV
VIL	Input LOW Voltage Single Ended	3065		3390	3130		3455	3190		3515	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Note 11.)	2.0		5.0	2.0		5.0	2.0		5.0	V
IIН	Input HIGH Current			150			150			150	μΑ
۱	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μA

DC CHARACTERISTICS, PECL ($V_{CC} = 5.0V \pm 0.5V$, $V_{EE} = 0V$) (Note 12.)

NOTE: 10EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

9. $V_{CC} = 5.0V$, $V_{EE} = 0V$, all other pins floating. 10. All loading with 50 ohms to V_{CC} -2.0 volts. 11. V_{IHCMR} min varies 1:1 with V_{EE} , max varies 1:1 with V_{CC} .

12. Input and output parameters vary 1:1 with V_{CC}.

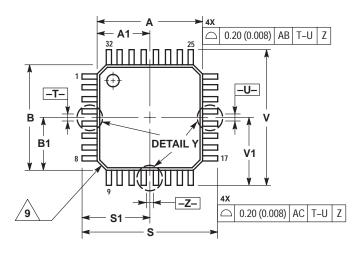
			–40°C			25°C			85°C			
Symbol	Characteristic	Mi	n '	Тур	Мах	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency (Note 13.)			3.0			3.0			3.0		GHz
^t PLH, ^t PHL	Propagation Delay to Output Differential						190					ps
^t SKEW	Duty Cycle Skew (Note 14.)			5.0			5.0	20		5.0	20	ps
^t JITTER	Cycle-to-Cycle Jitter		1	TBD			TBD			TBD		ps
Vpp	Input Voltage Swing (Diff.)	15	0	800	1200	150	800	1200	150	800	1200	mV
t _r t _f	Output Rise/Fall Times ((20% – 80%)	2					120					ps

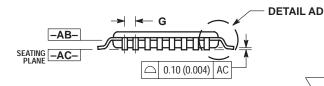
AC CHARACTERISTICS (Vac = 0.0° Vec = -3.0° to -5.5°) or (Vac = 3.0° to 5.5° Vec = 0.0°

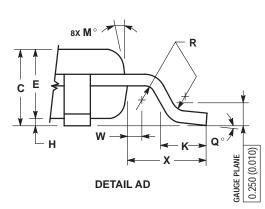
 13. F_{max} guaranteed for functionality only. V_{OL} and V_{OH} levels are guaranteed at DC only.
 14. Skew is measured between outputs under identical transitions. Duty cycle skew is defined only for differential operation when the delays are measured from the cross point of the inputs to the cross point of the outputs.

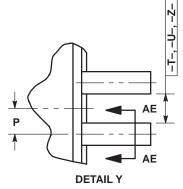
PACKAGE DIMENSIONS











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BASE METAL

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SECTION AE-AE

NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI 211 UNIVERSIDATING AND TOLERONOMO. C. CANADA STRATEGY 14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DATUM PLANE -AB- IS LOCATED AT BOTTOM
 OF LEAD AND IS COINCIDENT WITH THE LEAD
 INFORMATING FOR ATTACK AND ADDRESS AND ADDRES

OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE. 4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-. 5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-. 6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-. 7. DIMENSION D DOES NOT INCLUDE DAMBAR

7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL

PROTIRUSION. DAMBAR PROTIRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.520 (0.020). 8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003). 9. EXACT SHAPE OF EACH CORNER MAY VARY EDOM DEDICTION FROM DEPICTION.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	7.000	BSC	0.276	5 BSC	
A1	3.500) BSC	0.138	BSC 3	
В	7.000	BSC	0.276	5 BSC	
B1	3.500	BSC	0.138	BSC	
С	1.400	1.600	0.055	0.063	
D	0.300	0.450	0.012	0.018	
E	1.350	1.450	0.053	0.057	
F	0.300	0.400	0.012	0.016	
G	0.800	BSC	0.031 BSC		
Н	0.050	0.150	0.002	0.006	
J	0.090	0.200	0.004	0.008	
K	0.500	0.700	0.020	0.028	
Μ	12°	REF	12°	REF	
Ν	0.090	0.160	0.004	0.006	
Р	0.400			BSC	
Q	1°	5°	1°	5°	
R	0.150	0.250	0.006	0.010	
S	9.000	BSC	0.354	1 BSC	
S1	4.500	BSC	0.177	7 BSC	
V	9.000 BSC		0.354	4 BSC	
V1	4.500	BSC	0.177	7 BSC	
W	0.200			B REF	
Х	1.000	REF	0.039	9 REF	

<u>Notes</u>

<u>Notes</u>

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